

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

**Claim 1 (cancelled).**

**Claim 2 (currently amended).** The flexible board as set forth in claim 4, further comprising:

[[~~(e)~~]] (f) a first cover layer formed over a surface of said first ground layer; and

[[~~(f)~~]] (g) a second cover layer formed over a surface of said second ground layer.

**Claim 3 (original).** The flexible board as set forth in claim 2, further comprising electrically insulating adhesive layers sandwiched among said internal layer, said first and second ground layers, and said first and second cover layers.

**Claim 4 (currently amended).** A flexible board ~~comprising a ground line, said ground line~~ comprising:

(a) an internal layer;

(b) ~~a line formed in a first area of said internal layer, said line~~ a plurality of bus lines arranged on said internal layer, said plurality of bus lines radiating unnecessary radiation;

(c) a first ground layer formed on an upper surface of said internal layer, said first ground layer disallowing radiation to pass therethrough; ~~and~~

(d) a second ground layer formed on a lower surface of said internal layer, said second ground layer disallowing radiation to pass therethrough; and

(e) ground lines arranged at opposite sides of said plurality of bus lines, such that said first ground layer, said second ground layer and said ground lines surround said plurality of bus lines and establish a shield by which unnecessary radiation is prevented from being radiated outside of said plurality of bus lines.

**Claim 5 (original).** The flexible board as set forth in claim 4, wherein a plurality of through-holes is formed throughout said first ground layer, said internal layer, and said second ground layer.

**Claim 6 (currently amended).** The flexible board as set forth in claim 4, wherein a plurality of throughholes is formed throughout said first ground layer, said ground lines, and said second ground layer, said through-holes electrically connecting said first ground layer, said ground lines, and said second ground layer to one another.

**Claim 7 (cancelled).**

**Claim 8 (currently amended).** The method as set forth in claim 10, further comprising the steps of:

[[ (d) ]] (e) covering a surface of said first ground layer with a first cover layer; and

[[ (e) ]] (f) covering a surface of said second ground layer with a second cover layer.

**Claim 9 (original).** The method as set forth in claim 8, further comprising the step of forming electrically insulating adhesive layers among said internal layer, said first and second ground layers, and said first and second cover layers.

**Claim 10 (currently amended).** A method of fabricating a flexible board, comprising the steps of ~~forming a ground line by:~~

(a) ~~forming a line in a first area of an internal layer, said line plurality of bus lines on said internal layer, said plurality of bus lines radiating unnecessary radiation;~~

(b) covering an upper surface of said internal layer with a first ground layer which disallows radiation to pass therethrough; ~~and~~

(c) covering a lower surface of said internal layer with a second ground layer which disallows radiation to pass therethrough; and

(d) forming ground lines arranged at opposite sides of said plurality of bus lines, such that said first ground layer, said second ground layer and said ground lines surround said plurality of bus lines and establish a shield by which unnecessary radiation is prevented from being radiated outside of said plurality of bus lines.

**Claim 11 (previously presented).** The method as set forth in claim 10, further comprising the step of forming a plurality of through-holes throughout said first ground layer, said internal layer, and said second ground layer.

**Claim 12 (currently amended).** The method as set forth in claim 10, further comprising the step of forming a plurality of through-holes throughout said first ground layer, said ground lines, and said second ground layer so that said through-holes electrically connect said first ground layer, said ground lines, and said second ground layer to one another.

**Claim 13 (cancelled).**

**Claim 14 (currently amended).** The cellular phone as set forth in claim 16, further comprising:

[[ (e) ] ] (f) a first cover layer formed over a surface of said first ground layer;  
and

[[ (f) ] ] (g) a second cover layer formed over a surface of said second ground layer.

**Claim 15 (original).** The cellular phone as set forth in claim 14, further comprising electrically insulating adhesive layers sandwiched among said internal layer, said first and second ground layers, and said first and second cover layers.

**Claim 16 (currently amended).** A cellular phone including a flexible board, said flexible board comprising ~~a ground line comprised of:~~

(a) an internal layer;

(b) ~~a line formed in a first area of said internal layer, said line~~ a plurality of bus lines arranged on said internal layer, said plurality of bus lines radiating unnecessary radiation;

(c) a first ground layer formed on an upper surface of said internal layer, said first ground layer disallowing radiation to pass therethrough; and

(d) a second ground layer formed on a lower surface of said internal layer, said second ground layer disallowing radiation to pass therethrough; and

(e) ground lines arranged at opposite sides of said plurality of bus lines, such that said first ground layer, said second ground layer and said ground lines surround said plurality of bus lines and establish a shield by which unnecessary radiation is prevented from being radiated outside of said plurality of bus lines.

**Claim 17 (previously presented).** The cellular phone as set forth in claim 16, wherein a plurality of through-holes is formed throughout said first ground layer, said internal layer, and said second ground layer.

**Claim 18 (currently amended).** The cellular phone as set forth in claim 16, wherein a plurality of through-holes is formed throughout said first ground layer, said ground lines, and said second ground layer, said through-holes electrically connecting said first ground layer, said ground lines, and said second ground layer to one another.